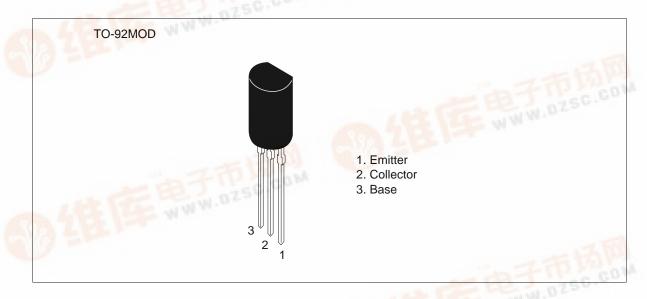
Silicon PNP Epitaxial

HITACHI

Application

- Low frequency power amplifier
- Complementary pair with 2SD667/A

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	2SB647	2SB647A	Unit
Collector to base voltage	V_{CBO}	-120	-120	V
Collector to emitter voltage	V_{CEO}	-80	-100	V
Emitter to base voltage	V_{EBO}	- 5	– 5	V
Collector current	I _c	-1	– 1	A
Collector peak current	i _{C(peak)}	-2	-2	A
Collector power dissipation	P _c	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

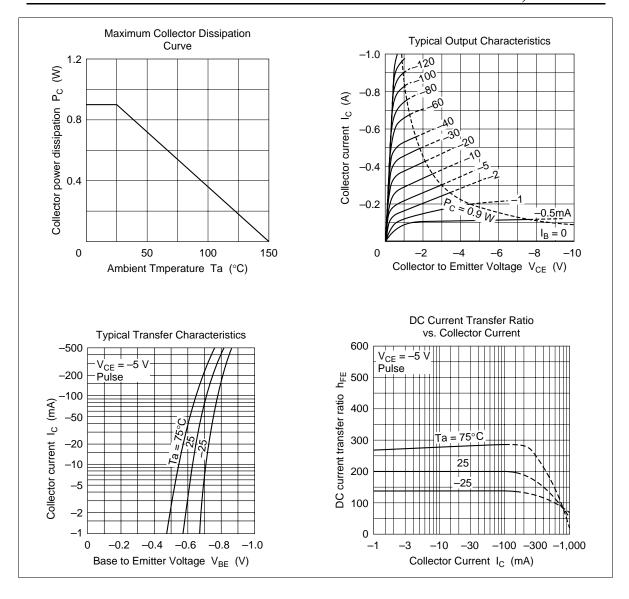
Electrical Characteristics ($Ta = 25^{\circ}C$)

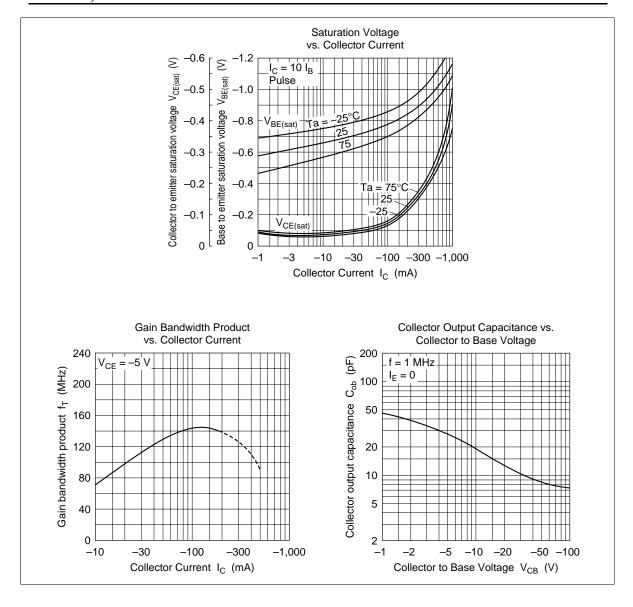
		2SB647		2SB647A					
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-120	_	_	-120	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-80	_	_	-100	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	- 5	_	_	V	$I_{E} = -10 \mu A, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	_	_	-10	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	60	_	320	60	_	200		$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}^{*2}$
	h _{FE2}	30	_	_	30	_	_		$V_{CE} = -5 \text{ V},$ $I_{C} = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$\boldsymbol{V}_{\text{CE(sat)}}$	_	_	-1	_	_	-1	V	$I_{\rm C} = -500 \text{ mA},$ $I_{\rm B} = -50 \text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	_	_	-1.5	_	_	-1.5	V	$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}^{*2}$
Gain bandwidth product	f _T	_	140	_	_	140	_	MHz	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	20	_	_	20	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0$ f = 1 MHz

Notes: 1. The 2SB647 and 2SB647A are grouped by h_{FE1} as follows.

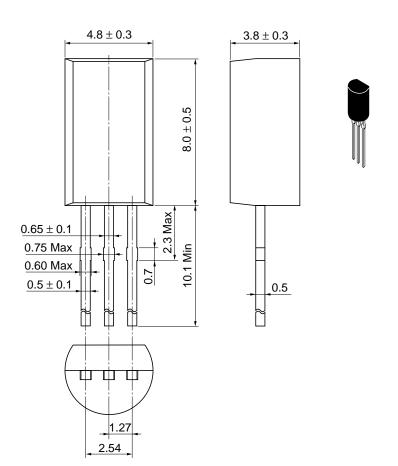
2. Pulse test

	В	С	D
2SB647	60 to 120	100 to 200	160 to 320
2SB647A	60 to 120	100 to 200	_









Cautions

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